

# RD3P01BAT

### Pch -100V -10A Power MOSFET

V <sub>DSS</sub>	-100V
R <sub>DS(on)</sub> (Max.)	240mΩ
I <sub>D</sub>	±10A
P <sub>D</sub>	25W

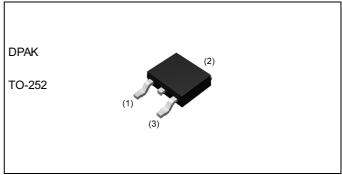
### Features

- 1) Low on resistance
- 2) High power small mold package
- 3) Pb-free plating; RoHS compliant
- 4) 100% Rg and UIS tested
- 5) Halogen free

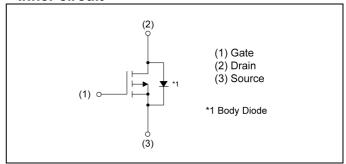
### Application

Switching

### Outline



### ●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	16
	Quantity (pcs)	2500
	Taping code	TL1
	Marking	RD3P01BAT

### ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	-100	V
Continuous drain current V <sub>GS</sub> = -10V		I <sub>D</sub> *1	±10	А
Pulsed drain current	l <sub>DP</sub> *2	±20	А	
Gate - Source voltage		$V_{GSS}$	±20	V
Avalanche current, single pulse		I <sub>AS</sub> *3	-5	Α
Avalanche energy, single pulse		E <sub>AS</sub> *3	1.7	mJ
Power dissipation		P <sub>D</sub> *1	25	W
Junction temperature		T <sub>j</sub>	150	°C
Operating junction and storage te	T <sub>stg</sub>	-55 to +150	°C	

### ●Thermal resistance

Parameter	Symbol	Values			Lleit
		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	4.90	°C/W

### ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min. Typ.		Max.	Offic	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = -1mA$	-100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = -1mA referenced to 25°C	-	-68	-	mV/°C	
Zero gate voltage drain current	$I_{DSS}$ $V_{DS} = -100V$ , $V_{GS} = 0V$		-	-	-1	μА	
Gate - Source leakage current	I <sub>GSS</sub>	$I_{GSS}$ $V_{GS} = \pm 20V, V_{DS} = 0V$		ı	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{GS(th)}$ $V_{DS} = V_{GS}$ , $I_D = -1mA$		-	-4.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta  V_{GS(th)}}{\Delta  T_j}$			5.1	-	mV/°C	
Static drain - source	D *4	V <sub>GS</sub> = -10V, I <sub>D</sub> = -5A	-	181	240	O	
on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = -6V, I <sub>D</sub> = -5A	-	210	270	mΩ	
Gate resistance	R <sub>G</sub> f = 1MHz, open drain		-	14	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = -5V, I <sub>D</sub> = -5A	4.4	-	-	S	

<sup>\*1</sup> T<sub>c</sub>=25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = -50V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>i</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Pulsed

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Dorameter	Cumbal	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	660	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = -50V	-	41	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	1	38	-	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq -50V, V_{GS} = -10V$	-	12	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = -5A	1	14	1	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 10\Omega$	-	59	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	45	-	

## • Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymah al	Conditions		Values			l lait			
Parameter	Symbol			Min.	Тур.	Max.	Unit			
Total gate charge	Q <sub>g</sub> *4	Qg*4	-	O *4		V <sub>GS</sub> = -10V	-	19.4	-	
Total gate charge				V <sub>DD</sub> ≃ <b>-</b> 50V		-	12.3	-		
Gate - Source charge		I <sub>D</sub> = -10A	V <sub>GS</sub> = -6V	-	3.8	-	nC			
Gate - Drain charge	Q <sub>gd</sub> *4			-	6.4	-				

### ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25°C	1	-	-10	Α
Pulse forward current	I <sub>SP</sub> *2	1 <sub>a</sub> - 25 C	-	-	-20	Α
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = -10A	-	-	-1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = -10A, V <sub>GS</sub> =0V	-	42	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/μs	-	61	-	nC

Fig.1 Power Dissipation Derating Curve

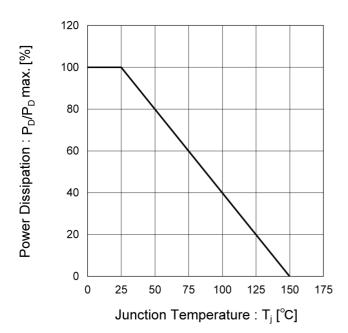
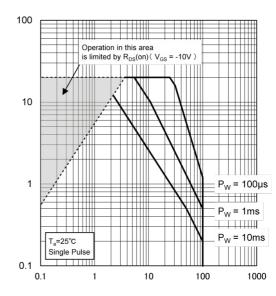


Fig.2 Maximum Safe Operating Area



Drain Current : -l<sub>D</sub> [A]

Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

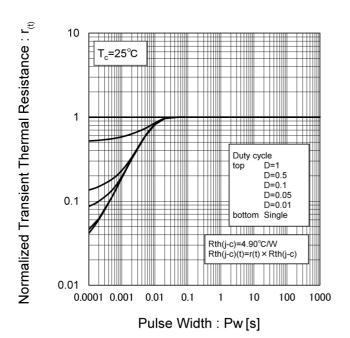
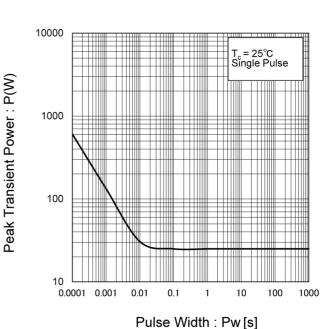


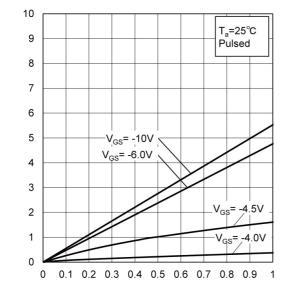
Fig.4 Single Pulse Maximum Power Dissipation



Drain Current: -l<sub>D</sub> [A]

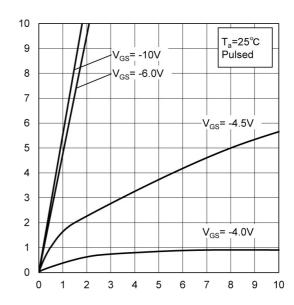
### • Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.6 Typical Output Characteristics(II)



Drain Current : -I<sub>D</sub> [A]

Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

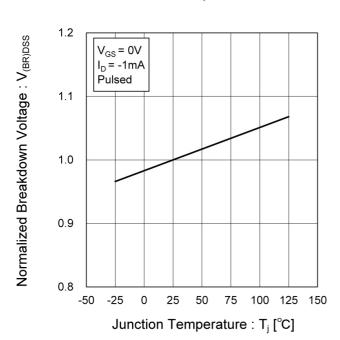


Fig.8 Typical Transfer Characteristics

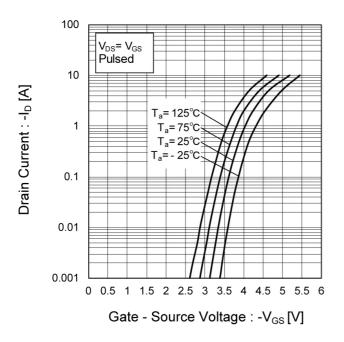


Fig.9 Gate Threshold Voltage vs.

Junction Temperature

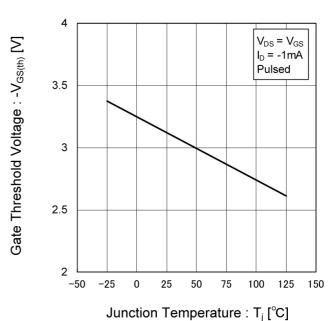


Fig.10 Forward Transfer Admittance vs.
Drain Current

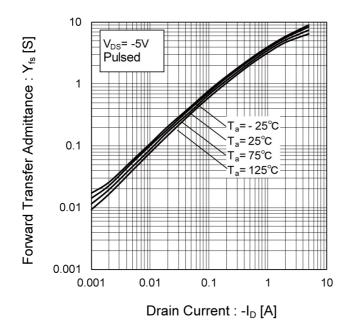


Fig.11 Drain Current Derating Curve

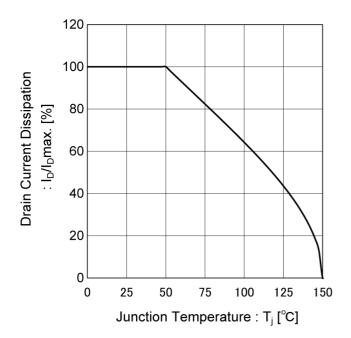


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

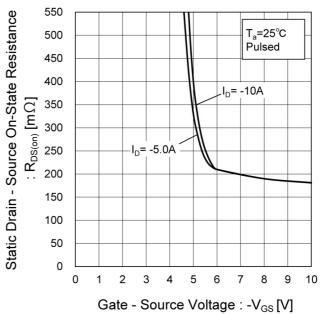


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

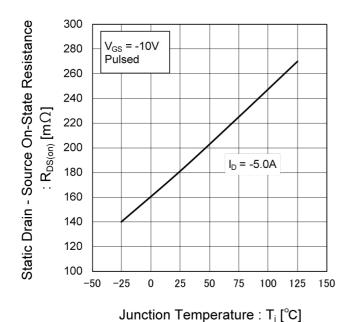


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

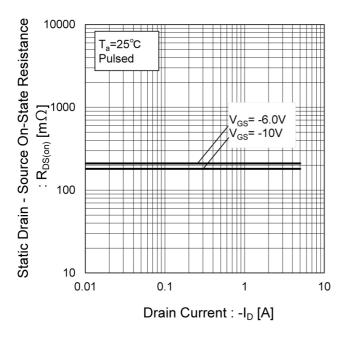


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

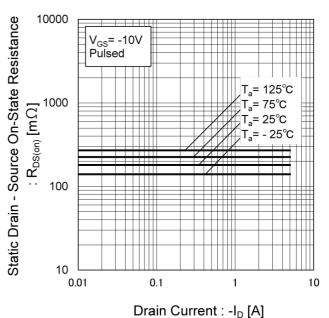


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

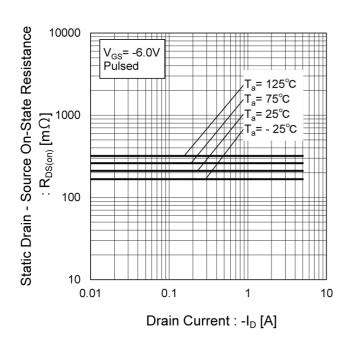


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

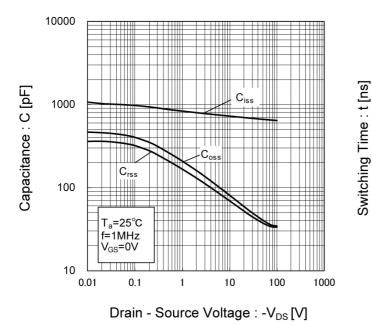


Fig.18 Switching Characteristics

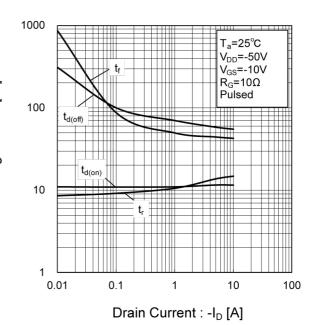
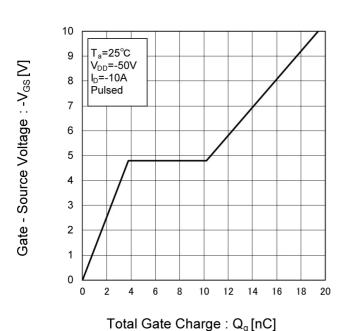


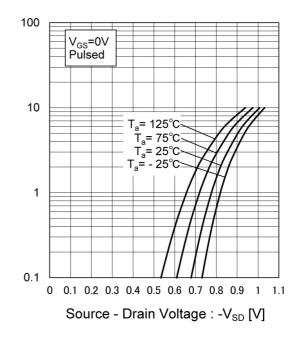
Fig.19 Typical Gate Charge



Source Current : -I<sub>s</sub> [A]

Fig.20 Source Current vs.

Source Drain Voltage



### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

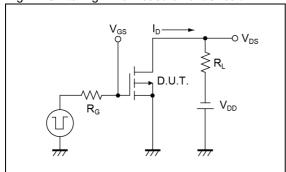


Fig.2-1 Gate Charge Measurement Circuit

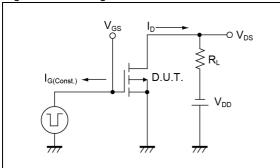


Fig.3-1 Avalanche Measurement Circuit

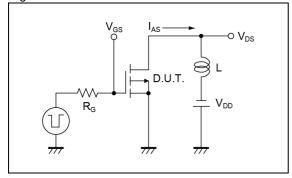


Fig.1-2 Switching Waveforms

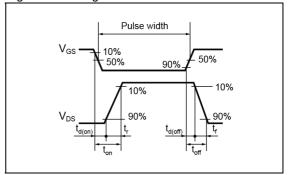


Fig.2-2 Gate Charge Waveform

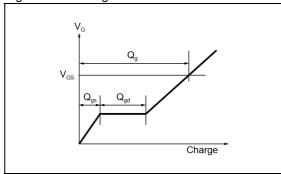
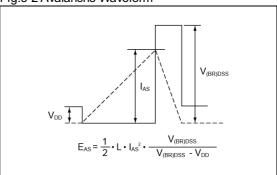
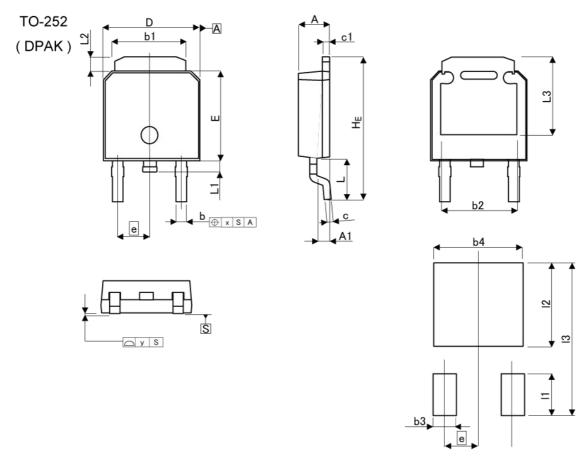


Fig.3-2 Avalanche Waveform



### Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	80	0.1	89
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.1	14
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.2	209
х	-	0.25	(-)	0.010
у	-	0.10		0.004
DIM	MILIME	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
b3	-	1.15	1-1	0.045
b4	-	5.55	( <b>.</b> 5)	0.219
I1	-	2.77	(=)	0.109
12	-	5.50	(F)	0.217
13	-	10.40	-	0.409

Dimension in mm/inches



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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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